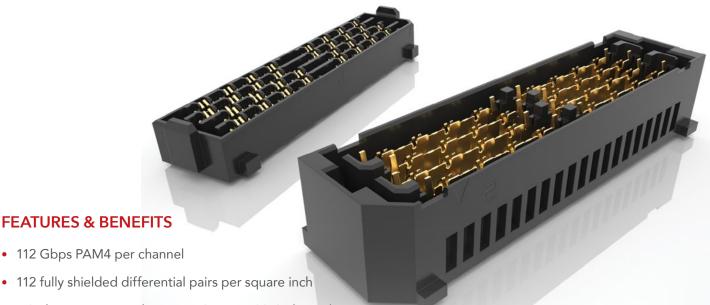


EXTREME PERFORMANCE HIGH-DENSITY ARRAYS

(0.80 mm) .0315" x (1.80 mm) .071" PITCH



- 112 fully shielded differential pairs per square inch
- 4.0 Tbps aggregate data rate 9 IEEE, 400 G channels
- Extremely low crosstalk to 40 GHz+
- Incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- 40% less space vs traditional arrays with the same data throughout







High-speed mezzanine connector and cable in one product family



BGA attach to board for greater density and optimized trace breakout region



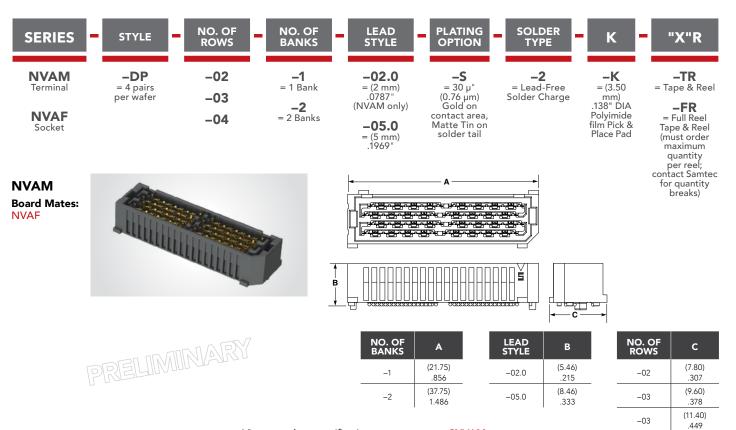
Guaranteed two points of contact to ensure a more reliable connection

KEY SPECIFICATIONS

STACK HEIGHTS	TOTAL PAIRS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
7 mm & 10 mm	Up to 32 pairs	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	2.1 A per pin (signal) 9.6 A per pin (ground)	200 VAC	Yes



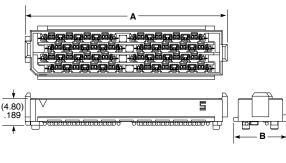
0.80 mm x 1.80 mm PITCH • EXTREME PERFORMANCE ARRAYS



View complete specifications at: samtec.com?NVAM

NVAF Board Mates: NVAM





AGGREGATE DATA RATE (NRZ)

	NO. OF BANKS	A				
	-1	(20.25) .797				
	-2	(36.25) 1.427				
ļ	NO. OF ROWS	В				
] +		(6.00) .236				
-	ROWS	(6.00)				

.378

MATED HEIGHTS*						
	NVAM LEAD STYLE					
NVAF LEAD STYLE	-02.0	-05.0				
-05.0	(7.00) .276	(10.00) .394				

	NVAM LEAD STYLE			448 Gbps	672 Gbps	896 Gbps		1344 Gbps	1792 Gbps
VAF LEAD STYLE	-02.0	-05.0		1 Bank		2 Bank			Gups
05.0	5.0 (7.00) .276 (10.0	(10.00) 204	2.00\ 204	2 Row	3 Row	4 Row	2 Row	3 Row	4 Row
-05.0		(10.00) .394	8 Pairs	12 Pairs	16 Pairs		24 Pairs	32 Pairs	
ation and distinct will offer a second be table									

^{*}Processing conditions will affect mated height.

Notes:

Some sizes, styles and options are non-standard, non-returnable

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